

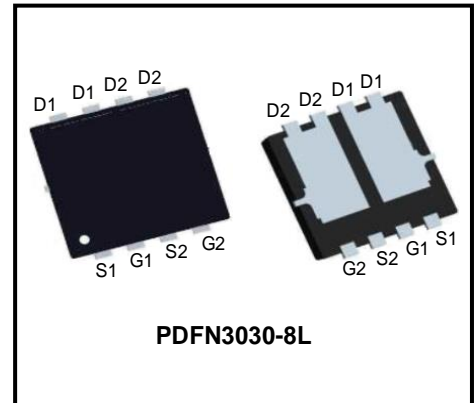
30V Dual N-Channel Enhancement Mode Power MOSFET

Description

WMQ40DN03T1 uses advanced power trench technology that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance.

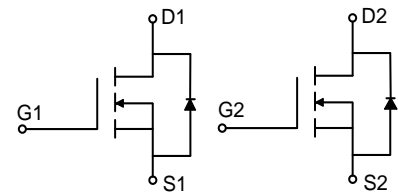
Features

- $V_{DS} = 30V$, $I_D = 40A$
 $R_{DS(on)} < 9m\Omega @ V_{GS} = 10V$
 $R_{DS(on)} < 14m\Omega @ V_{GS} = 4.5V$
- Green Device Available
- Low Gate Charge
- Advanced High Cell Density Trench Technology
- 100% EAS Guaranteed



Applications

- Power Management Switches
- DC/DC Converter



Absolute Maximum Ratings ($T_A = 25^\circ C$, unless otherwise noted)

Parameter		Symbol	Value	Unit
Drain-Source Voltage		V_{DS}	30	V
Gate-Source Voltage		V_{GS}	± 20	V
Continuous Drain Current	$T_C = 25^\circ C$	I_D	40	A
	$T_C = 100^\circ C$		25.3	
Pulsed Drain Current ¹		I_{DM}	160	A
Single Pulse Avalanche Energy ²		EAS	31.2	mJ
Total Power Dissipation	$T_C = 25^\circ C$	P_D	28.4	W
Operating Junction and Storage Temperature Range		T_J, T_{STG}	-55 to 150	$^\circ C$

Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient ³	$R_{\theta JA}$	73	$^\circ C/W$
Thermal Resistance from Junction-to-Case	$R_{\theta JC}$	4.4	$^\circ C/W$

Electrical Characteristics (T_J = 25°C, unless otherwise noted)

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	30	-	-	V
Gate-Body Leakage current	I _{GSS}	V _{DS} = 0V, V _{GS} = ±20V	-	-	±100	nA
Zero Gate Voltage Drain Current	T _J =25°C	V _{DS} = 30V, V _{GS} = 0V	-	-	1	μA
	T _J =100°C		-	-	100	
Gate-Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	1.0	1.6	2.5	V
Drain-Source On-Resistance ⁴	R _{DS(on)}	V _{GS} = 10V, I _D = 8A	-	7	9	mΩ
		V _{GS} = 4.5V, I _D = 6A	-	10.5	14	
Forward Transconductance ⁴	g _{fs}	V _{DS} = 10V, I _D = 5A	-	20	-	S
Dynamic Characteristics⁵						
Input Capacitance	C _{iss}	V _{DS} = 15V, V _{GS} = 0V, f = 1MHz	-	1390	-	pF
Output Capacitance	C _{oss}		-	178	-	
Reverse Transfer Capacitance	C _{rss}		-	141	-	
Gate Resistance	R _g	f = 1MHz	-	2.8	-	Ω
Switching Characteristics⁵						
Total Gate Charge	Q _g	V _{GS} = 4.5V, V _{DS} = 15V, I _D = 10A	-	9.5	-	nC
Gate-Source Charge	Q _{gs}		-	2.5	-	
Gate-Drain Charge	Q _{gd}		-	1.9	-	
Turn-On Delay Time	t _{d(on)}	V _{GS} = 10V, V _{DD} = 15V, R _G = 3Ω, I _D = 10A	-	8.3	-	ns
Rise Time	t _r		-	25	-	
Turn-Off Delay Time	t _{d(off)}		-	13	-	
Fall Time	t _f		-	6.2	-	
Reverse Recovery Time	t _{rr}	I _F = 10A, dI _F /dt = 100A/μs	-	9	-	ns
Reverse Recovery Charge	Q _{rr}		-	2	-	nC
Drain-Source Body Diode Characteristics						
Diode Forward Voltage ⁴	V _{SD}	I _S = 1A, V _{GS} = 0V	-	-	1.2	V
Continuous Source Current	T _C =25°C	I _S	-	-	40	A

Note :

1. Repetitive rating, pulse width limited by junction temperature T_{J(MAX)} = 150°C.
2. The EAS data shows Max. rating . The test condition is V_{DD} = 25V, V_{GS} = 10V, L = 0.1mH, I_{AS} = 25A.
3. The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
4. The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%.
5. This value is guaranteed by design hence it is not included in the production test.

Typical Characteristics

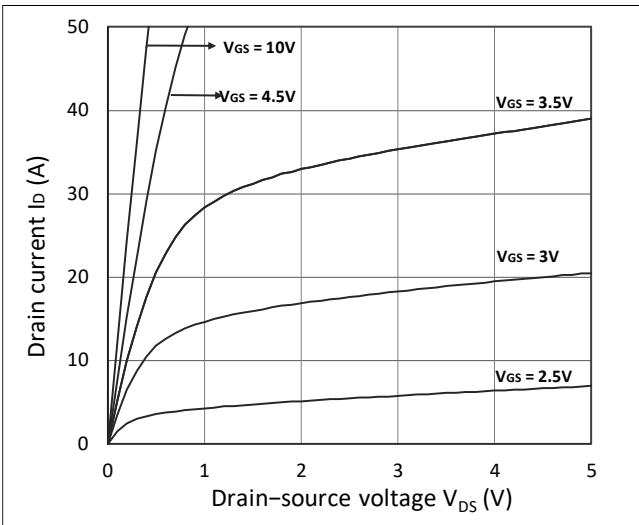


Figure 1. Output Characteristics

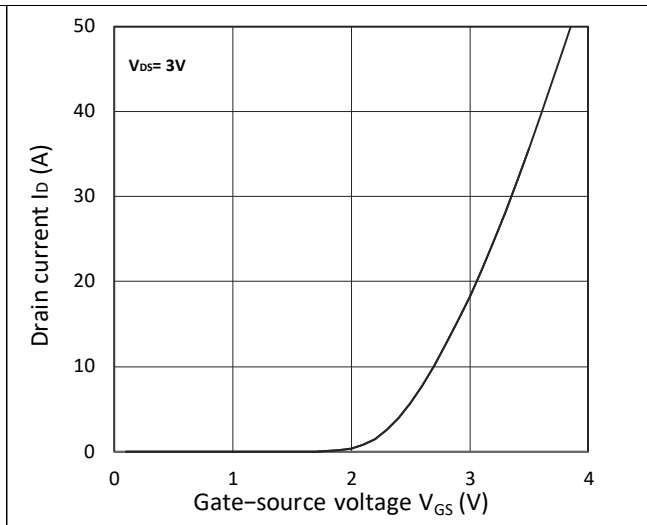


Figure 2. Transfer Characteristics

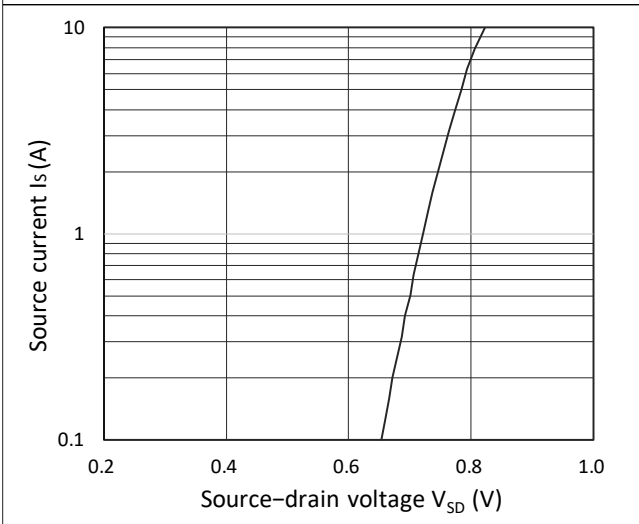


Figure 3. Forward Characteristics of Reverse

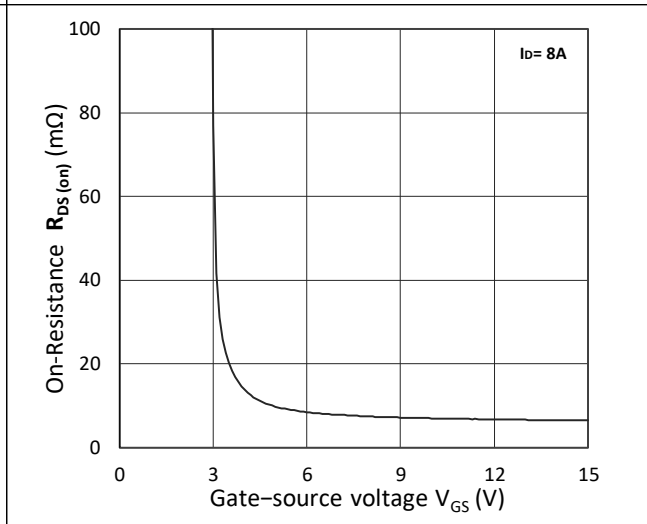


Figure 4. $R_{DS(on)}$ vs. V_{GS}

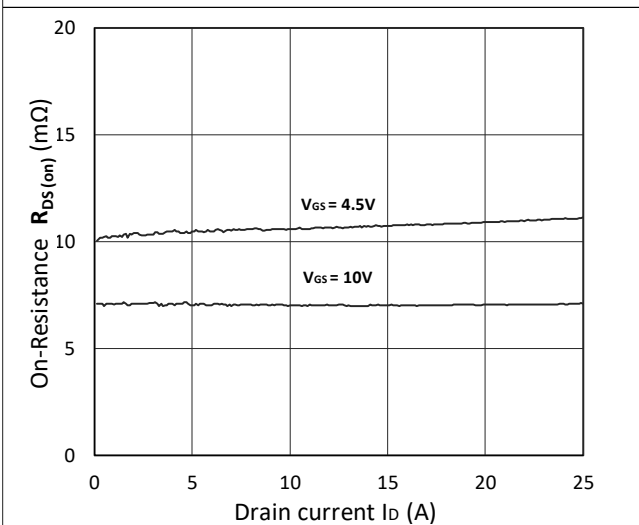


Figure 5. $R_{DS(on)}$ vs. I_D

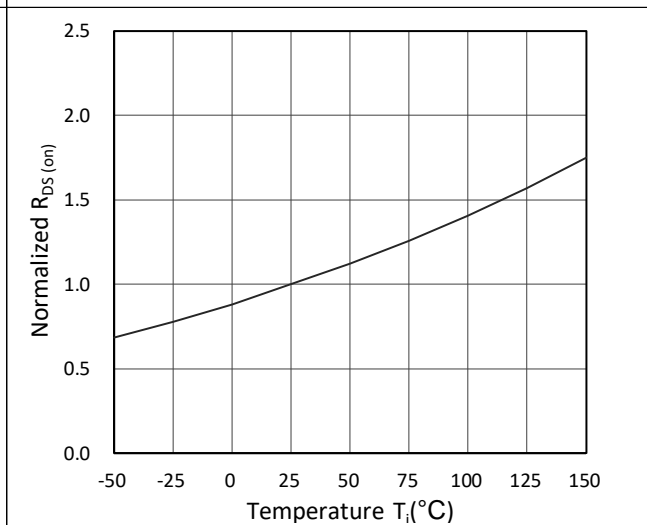


Figure 6. Normalized $R_{DS(on)}$ vs. Temperature

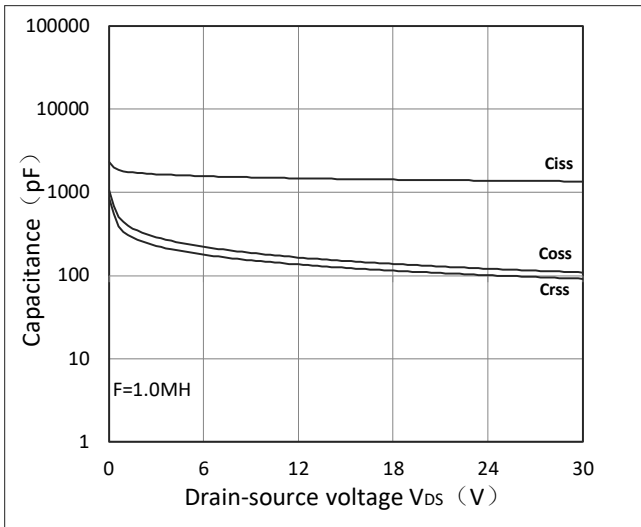


Figure 7. Capacitance Characteristics

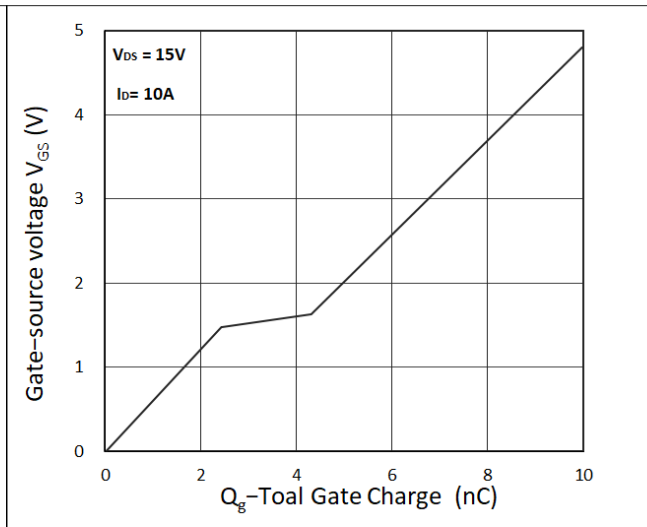


Figure 8. Gate Charge Characteristics

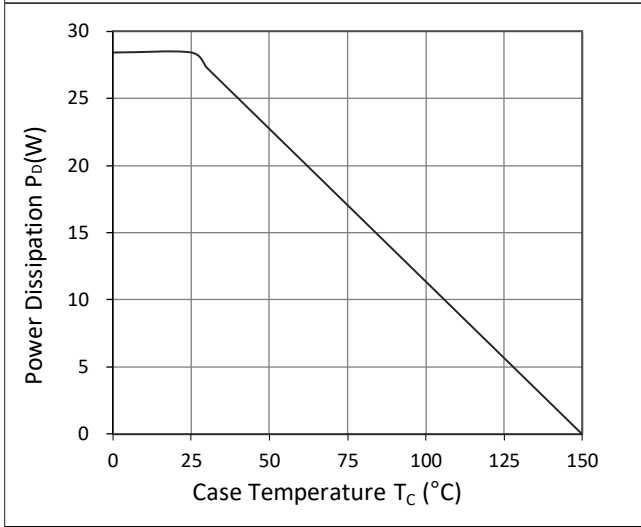


Figure 9. Power Dissipation

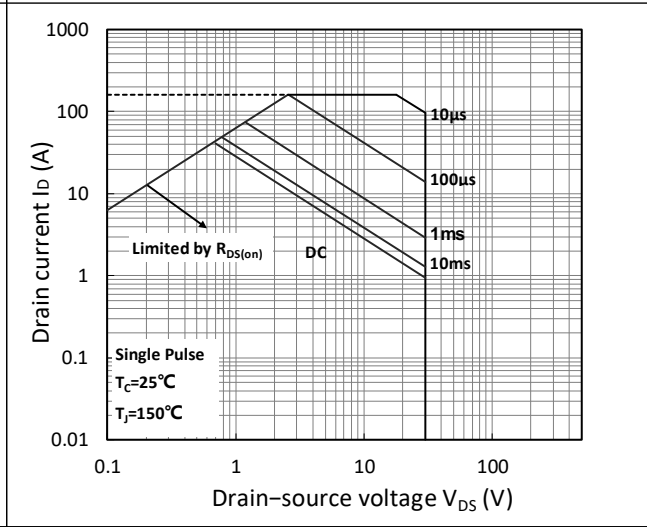


Figure 10. Safe Operating Area

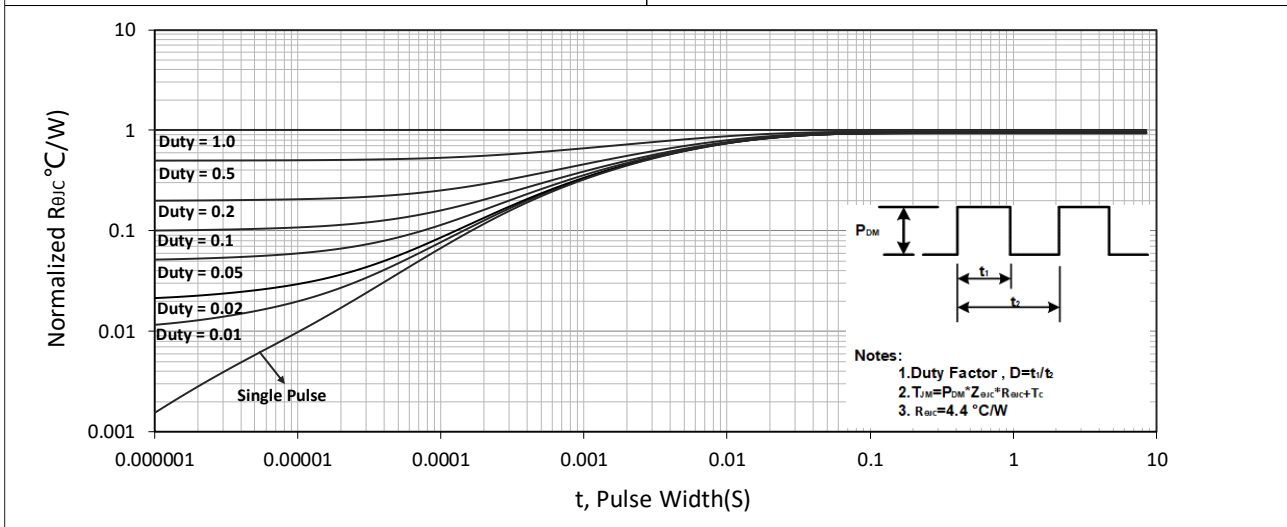


Figure 11. Normalized Maximum Transient Thermal Impedance

Test Circuit

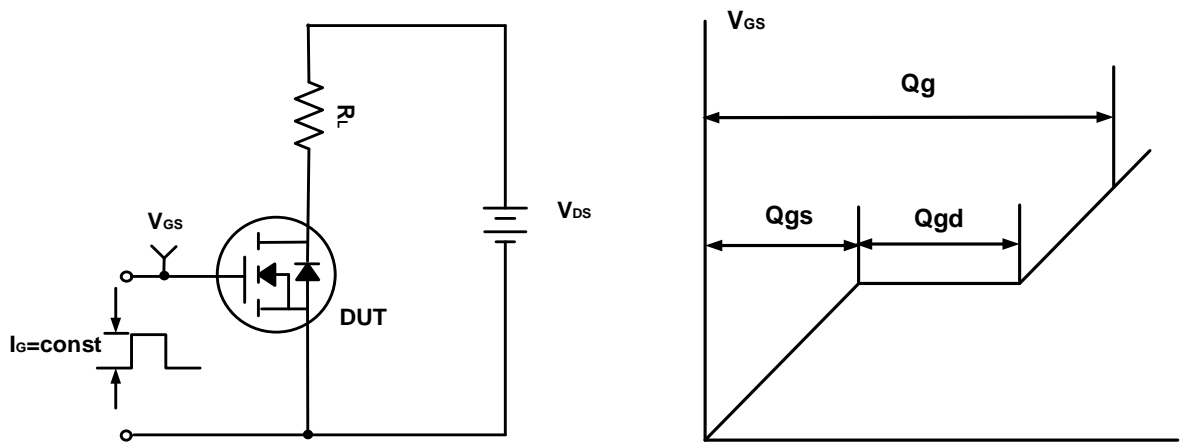


Figure A. Gate Charge Test Circuit & Waveforms

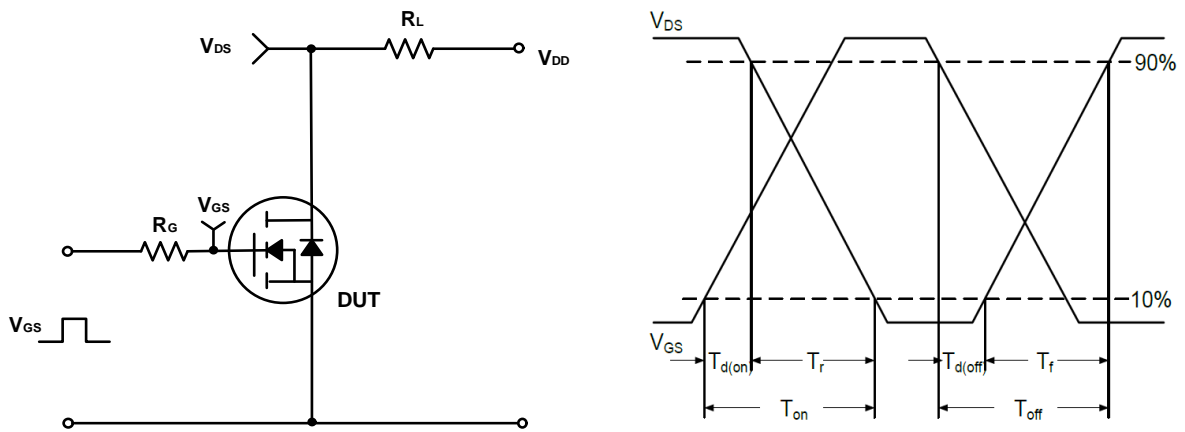


Figure B. Switching Test Circuit & Waveforms

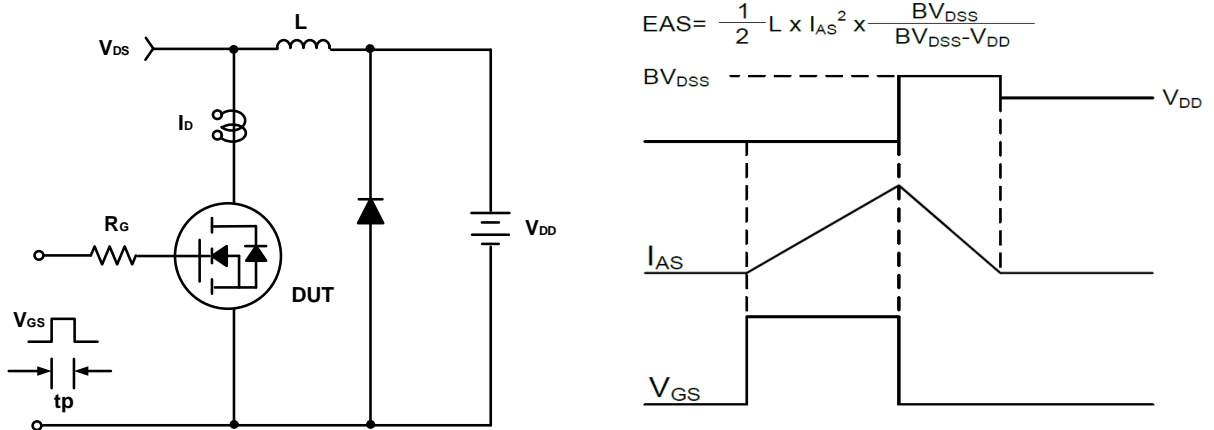
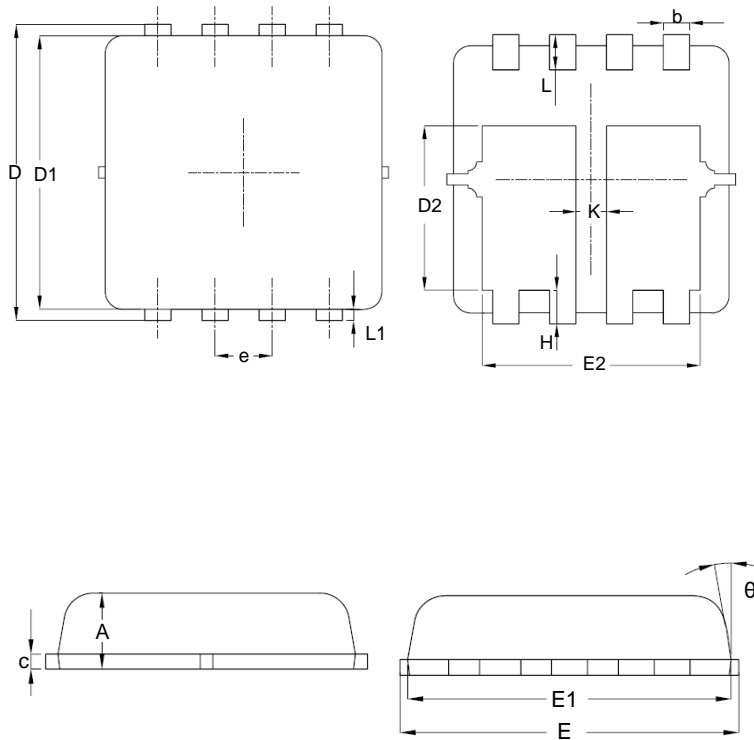


Figure C. Unclamped Inductive Switching Circuit & Waveforms

Mechanical Dimensions for PDFN3030-8L



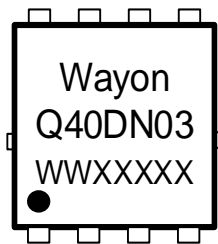
COMMON DIMENSIONS

SYMBOL	MM	
	MIN	MAX
A	0.70	0.95
b	0.20	0.40
c	0.10	0.25
D	3.15	3.45
D1	2.90	3.20
D2	1.53	1.98
E	3.00	3.40
E1	3.00	3.20
E2	2.15	2.75
e	0.65BSC	
H	0.30	0.52
L	0.30	0.50
L1	0.15REF	
K	0.28	0.48
θ	-	12°

Ordering Information

Part	Package	Marking	Packing method
WMQ40DN03T1	PDFN3030-8L	Q40DN03	Tape and Reel

Marking Information



Q40DN03 = Device code

WWXXXXX= Date code


Contact Information

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